Product End-of-Life Disassembly Instructions

Product Category: Servers
Marketing Name / Model [List multiple models if applicable.]
HP ProLiant DL160SE G6

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	6
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	Depending on power supply model.	5
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink,	Include the cartridges, print heads, tubes, vent	0

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including liquids, semi-liquids (gel/paste) and toner	chambers, and service stations.	
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Driver	T-15
Philps Driver	# 2
Flat Head Screw Driver	Medium

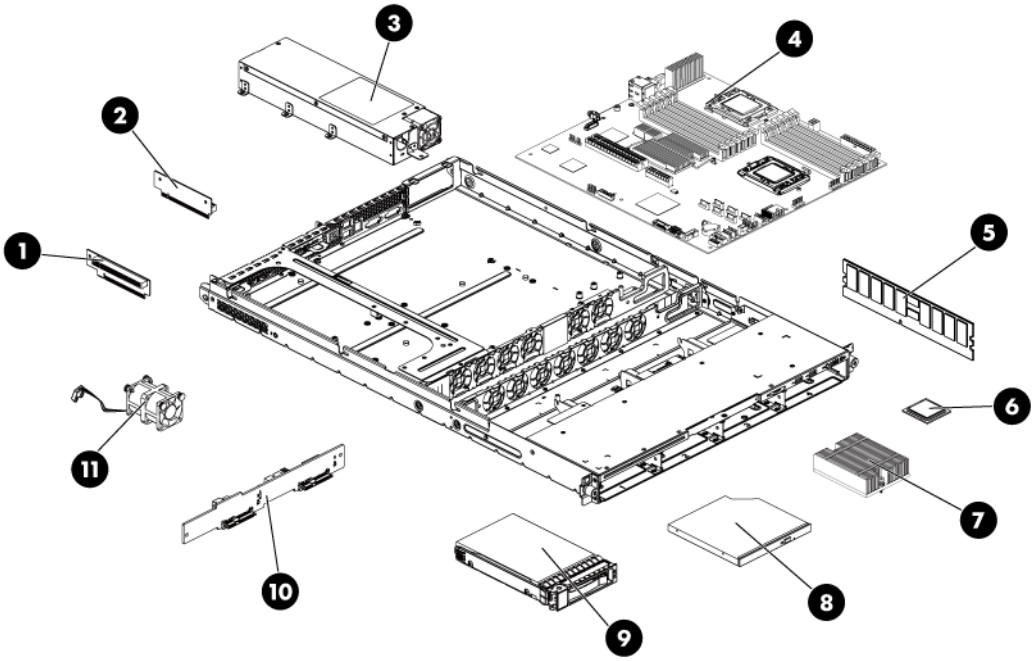
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

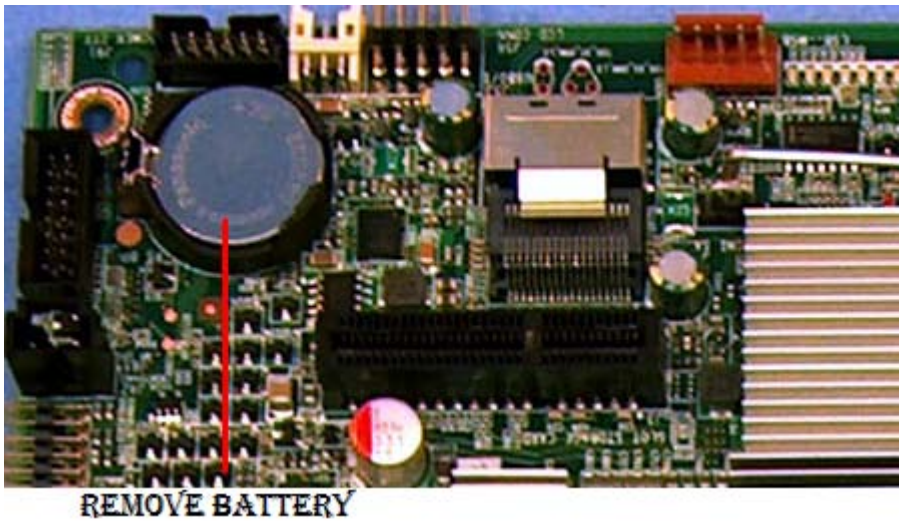
1. System Board Battery – Remove the top cover and locate the battery on the system board. With a medium flat head screw driver remove the battery and dispose of properly.
2. Capacitors > 2.5CM – Remove the power supply(s) from the system. With #2 Philips screw driver remove the screws securing the top cover and the heatsinks in the P/S then locate the capacitors and pry from the PCB with a medium flat head screw driver and dispose of properly
3. BBWC Battery – With a medium flat head screw driver remove the BBWC battery and dispose of properly.
4.
5.
6.
7.
8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

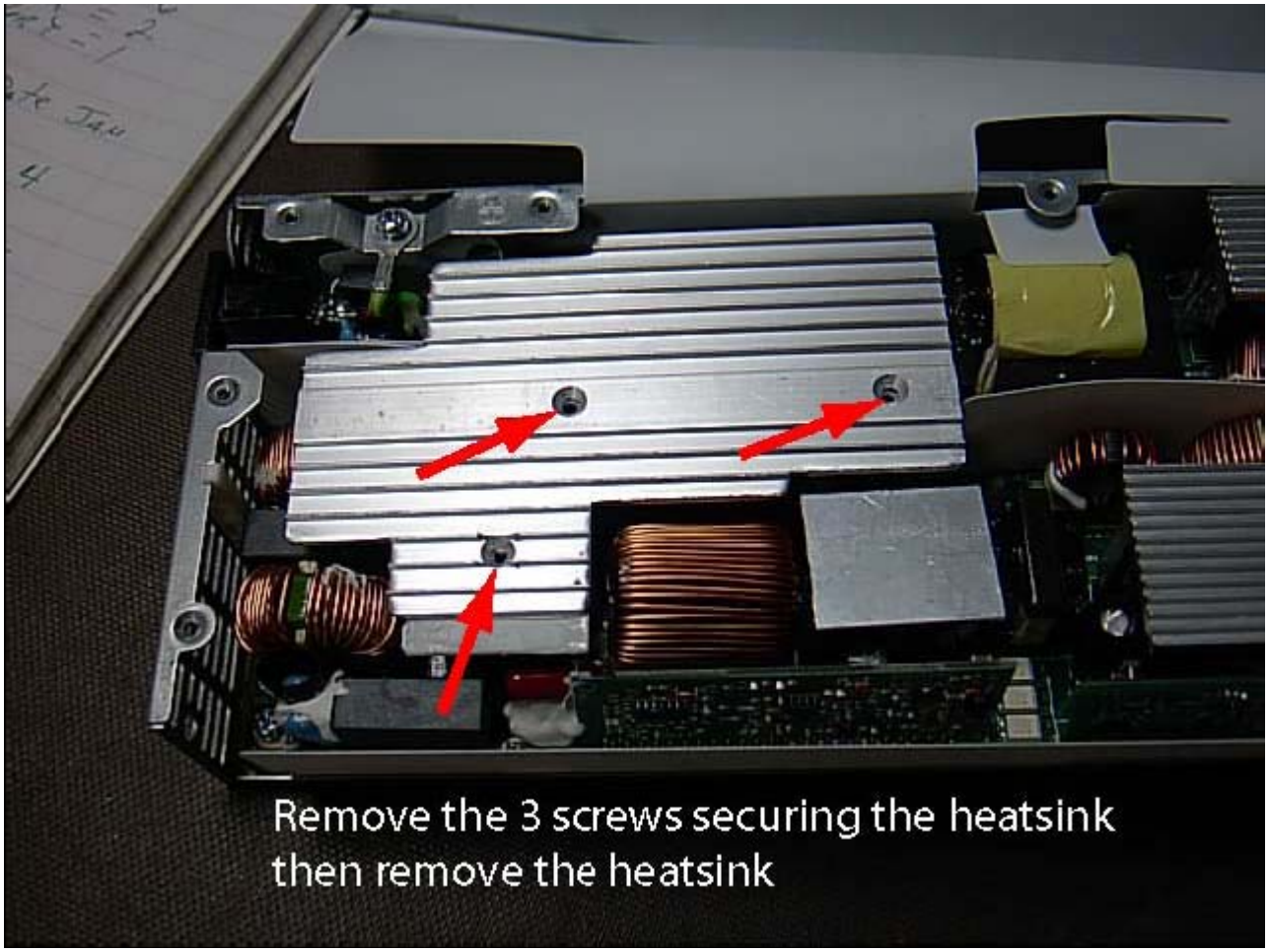
Attachment 1 – Disassembly Diagram
Attachment 2 – System Battery Location
Attachment 3, 4, 5, 6, 7, 8, 9, 10 - Capacitor location by model number of supply
Attachment 11- Location of BBWC Battery



Attachment 1

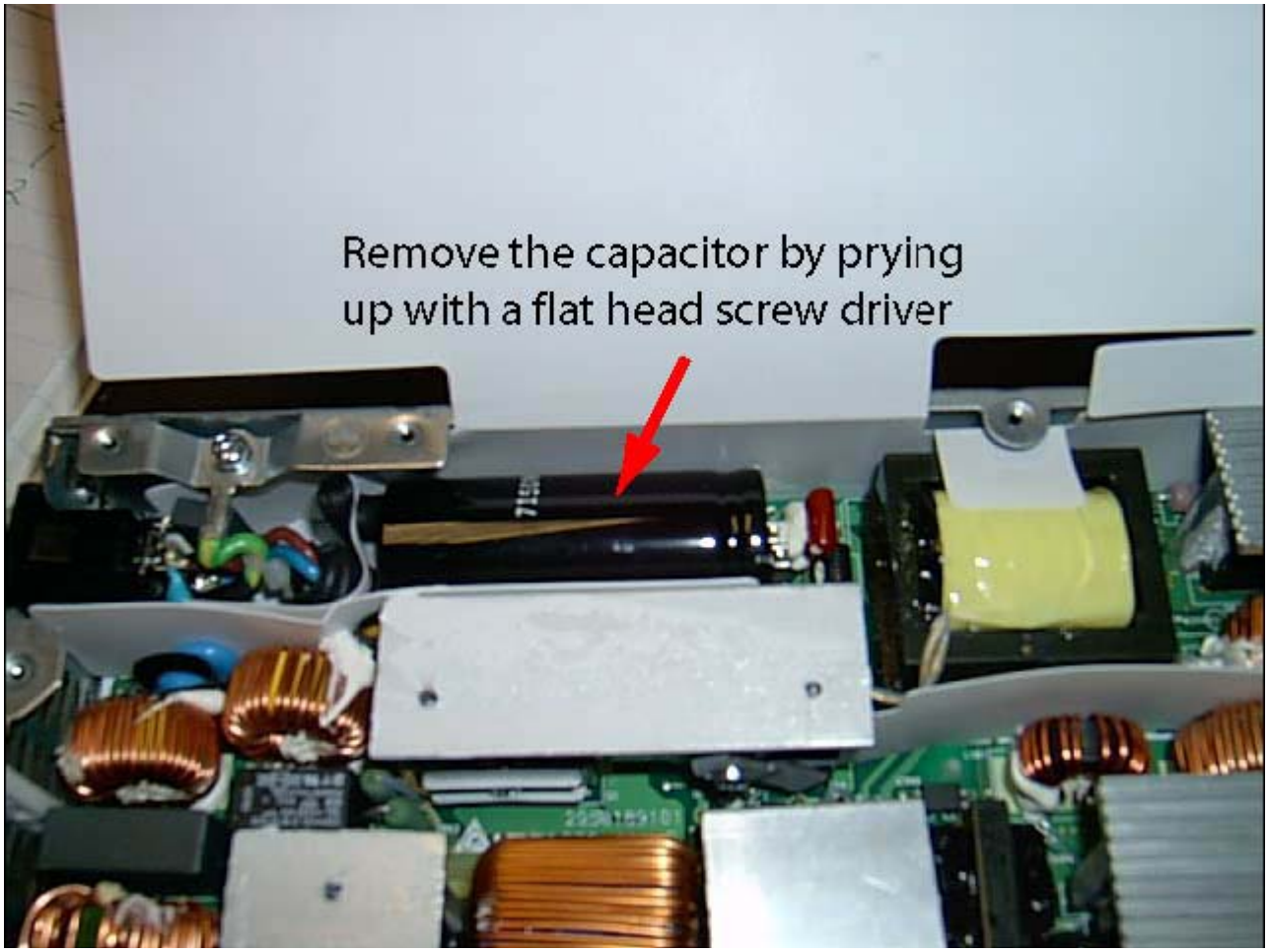


Attachment 2



Model Number DPS-650MBA

Attachment 3



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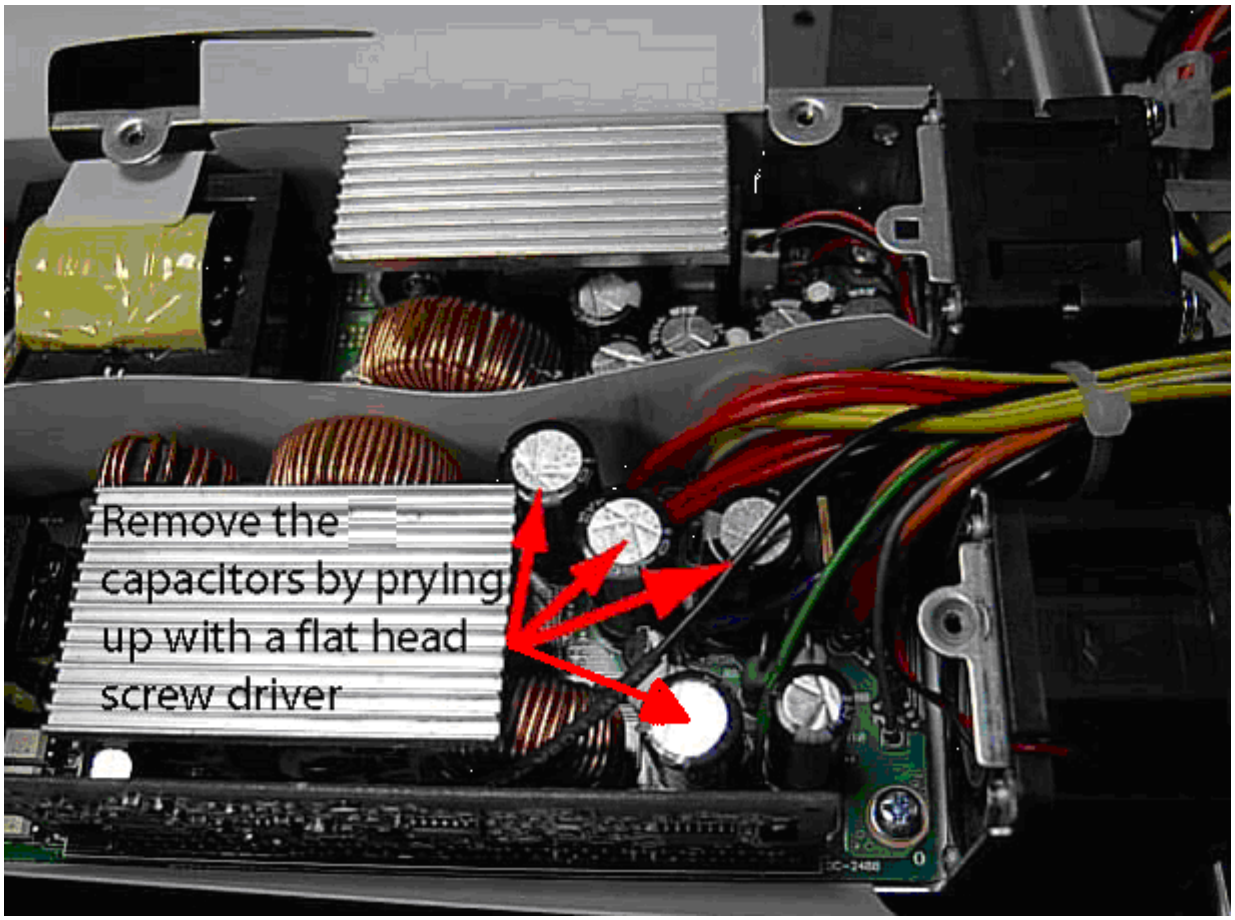
Attachment 4



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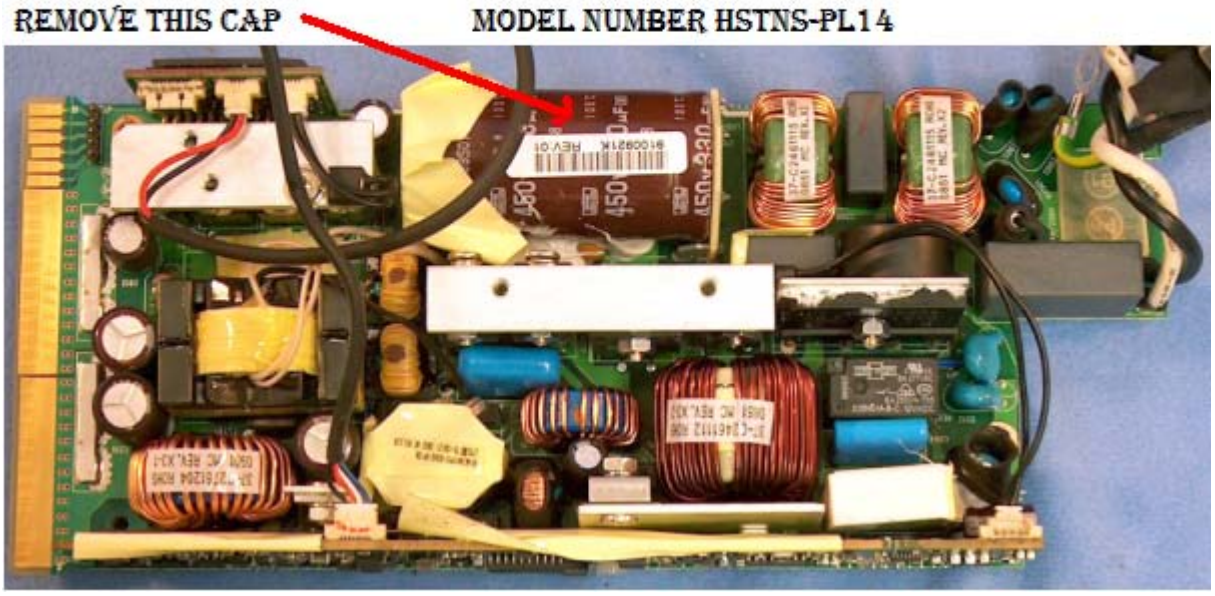
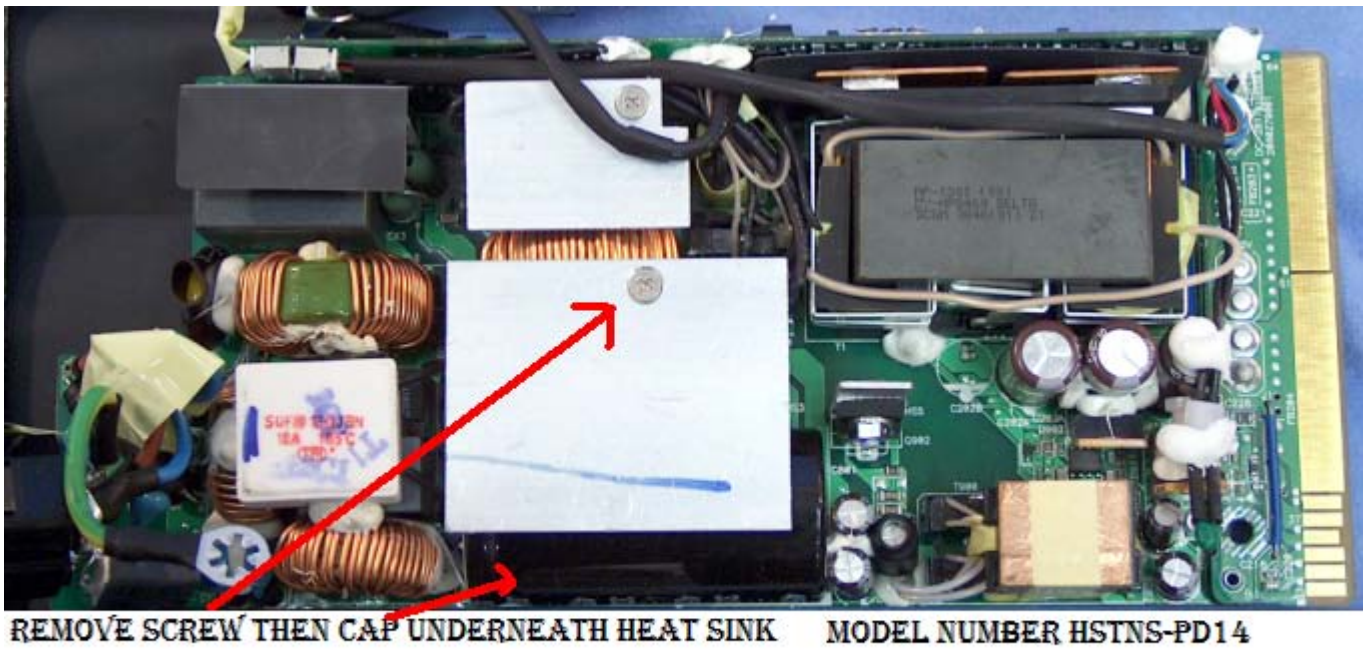
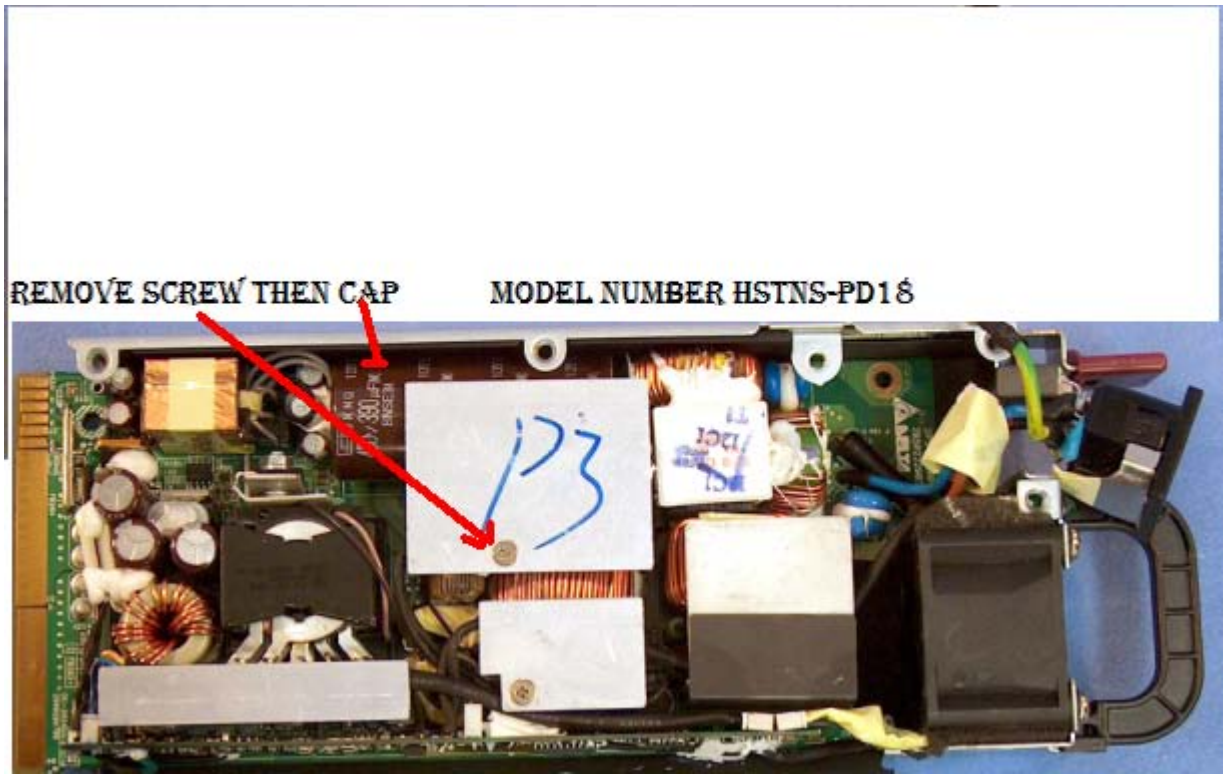
Attachment 5



Attachment 6

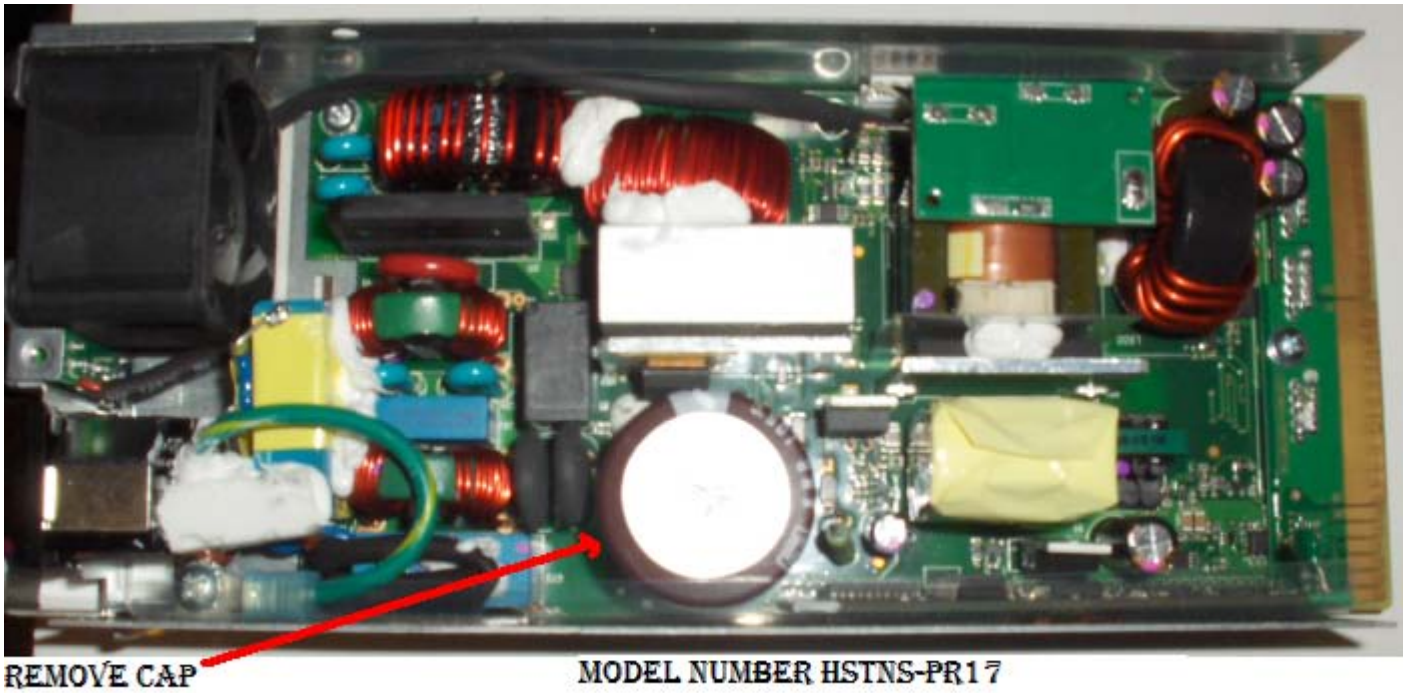


Attachment 7

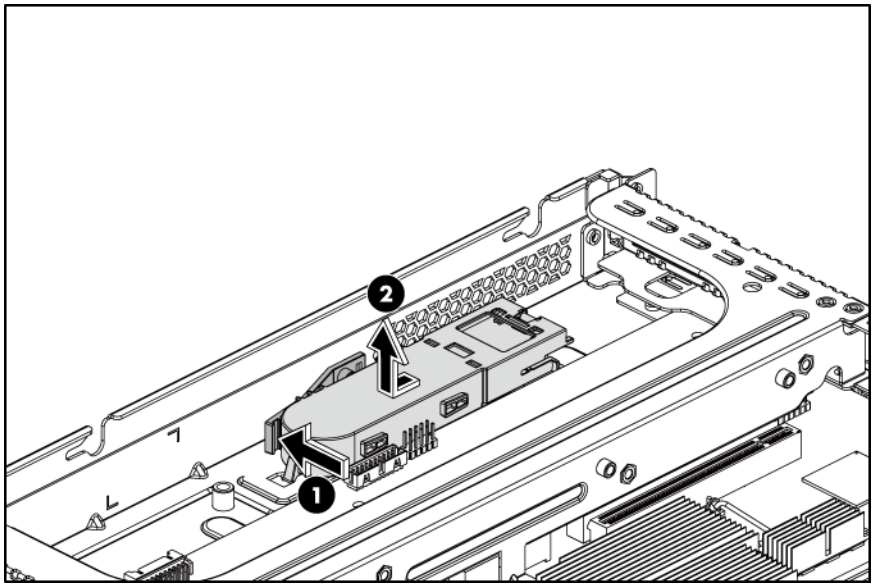


Attachment 8

Attachment 9



Attachment 10



Attachment 11